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AMD Mobile "Carrizo" Family of APUs Designed to Deliver Significant Leap in Performance, Energy Efficiency in 2015

2015 AMD Mobile Roadmap Adds "Carrizo" and "Carrizo-L" SoCs to APU Lineup

SINGAPORE -- (Marketwired) -- 11/20/14 -- AMD (NYSE: AMD) today at its Future of Compute event announced the addition of its first high performance system-on-a-chip (SoC), codenamed "Carrizo", and a mainstream SoC codenamed "Carrizo-L" as part of the company's 2015 AMD Mobile APU family roadmap. In collaboration with hardware and software partners, these new 2015 AMD Mobile APUs are designed as complete solutions for gaming, productivity applications, and ultra high-definition 4K experiences. With support for Microsoft® DirectX® 12, OpenCL® 2.0, AMD's Mantle API, AMD FreeSync and support for Microsoft's upcoming Windows® 10 operating system, the 2015 AMD Mobile APU family enables the experiences consumers expect.

"We continue to innovate and build upon our existing IP to deliver great products for our customers," said John Byrne, senior vice president and general manager, Computing and Graphics business group, AMD. "AMD's commitment to graphics and compute performance, as expressed by our goal to improve APU energy efficiency 25x by 2020, combines with the latest industry standards and fresh innovation to drive the design of the 2015 AMD Mobile APU family. We are excited about the experiences these new APUs will bring and look forward to sharing more details in the first half of next year."

The flagship "Carrizo" processor will integrate the new x86 CPU core codenamed "Excavator" with next generation AMD Radeon™ graphics in the world's first Heterogeneous Systems Architecture (HSA) 1.0 compliant SoC. The "Carrizo-L" SoC integrates the CPU codenamed "Puma+" with AMD Radeon™ R-Series GCN GPUs and is intended for mainstream configurations. In addition, an AMD Secure Processor will be integrated into the "Carrizo" and "Carrizo-L" APUs, enabling ARM® TrustZone® across the entire family for the security commercial customers and consumers expect. Utilizing a single package infrastructure for "Carrizo" and "Carrizo-L," the 2015 AMD Mobile APU family simplifies partner designs across a broad range of commercial and consumer mobile systems.

"Carrizo" and "Carrizo-L," are scheduled to ship in 1H 2015, with laptop and All-in-One systems based on the 2015 AMD Mobile APU family expected in market by mid-year 2015.

Supporting Resources

- View video of AMD's John Byrne introducing the "Carrizo" codenamed APU
- More information on AMD Investor Relations
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About AMD
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Cautionary Statement
This document contains forward-looking statements concerning Advanced Micro Devices, Inc. ("AMD" or the "Company") including, among other things, the timing, availability, features and functionality of the AMD "Carrizo" APU, AMD "Carrizo-L" SoC and AMD "Carrizo"-based notebooks; and AMD's commitment to a 25x energy efficiency improvement by 2020 which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act. Forward-looking statements are commonly identified by words such as "would," "may," "expects," "believes," "plans," "intends," "projects," and other terms with similar meaning. Investors are cautioned that the forward-looking statements in this press release are based on current beliefs, assumptions and expectations, speak only as of the date of this press release and involve risks and uncertainties that could cause actual results to differ materially from current expectations. Investors are cautioned that the forward-looking statements in this document are based on current beliefs, assumptions and expectations, speak only as of the date of this document and involve risks and uncertainties that could cause actual results to differ materially from current expectations. Risks include the possibility that Intel Corporation's pricing, marketing and rebating programs, product bundling, standard setting, new product introductions or other activities may negatively impact AMD's plans; that AMD will require additional funding and may be unable to raise sufficient capital on favorable terms, or at all; that customers stop buying AMD's products or materially reduce their operations or demand for AMD's products; that AMD may be unable to develop, launch and ramp new products and technologies in the volumes that are required by the market at mature yields on a timely basis; that AMD's third-party foundry suppliers will be unable to transition AMD's products to advanced manufacturing process technologies in a timely and effective way or to manufacture AMD's products on a timely basis in sufficient quantities and using competitive process technologies; that AMD will be unable to obtain sufficient manufacturing capacity or components to meet demand for its products or will not fully utilize its projected manufacturing capacity needs at GLOBALFOUNDRIES, Inc. (GF) microprocessor manufacturing facilities; that AMD's requirements for wafers will be less than the fixed number of wafers that it agreed to purchase from GF or GF encounters problems that significantly reduce the number of functional die it receives from each wafer; that AMD is unable to successfully implement its long-term business strategy; that the completion and impact of the 2014 Restructuring Plan and AMD's transformation initiatives could adversely affect AMD; that AMD inaccurately estimates the quantity or type of products that its customers will want in the future or will ultimately end up purchasing, resulting in excess or obsolete inventory; that AMD is unable to manage the risks related to the use of its third-party distributors and add-in-board (AIB)

partners or offer the appropriate incentives to focus them on the sale of AMD's products; that AMD may be unable to maintain the level of investment in research and development that is required to remain competitive; that there may be unexpected variations in market growth and demand for AMD's products and technologies in light of the product mix that it may have available at any particular time; that global business and economic conditions will not improve or will worsen; that PC market conditions will not improve or will worsen; that PC market conditions will not improve or will worsen; that demand for computers will be lower than currently expected; and the effect of political or economic instability, domestically or internationally, on AMD's sales or supply chain. Investors are urged to review in detail the risks and uncertainties in the Company's Securities and Exchange Commission filings, including but not limited to the Quarterly Report on Form 10-Q for the quarter ended September 27, 2014.

Embedded Video Available

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